

### **REMARKS**

Claims 1 and 3-8 are now pending in the application. The Examiner is respectfully requested to reconsider and withdraw the rejections in view of the amendments and remarks contained herein.

### **SPECIFICATION**

The title was deemed non-descriptive. The title has been changed taking the Examiner's comments into account. Favorable consideration of the new title is respectfully requested.

### **REJECTION UNDER 35 U.S.C. § 103**

Claims 1, 2 and 6 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over JP 08-236,908 in combination with Speakman (U.S. Pat. No. 6,503,831). This rejection is respectfully traversed.

Claim 1 calls for a manufacturing method of a multilayer circuit board. The comprises the step of forming at least two wiring layers, an inter-layer insulating film provided between every adjacent two of the wiring layers, and conductive posts for providing electrical conductivity between the wiring layers. The step includes forming the inter-layer insulating film by changing the film thickness of the inter-layer insulating film according to a concavo-convex shape of an area where the inter-layer insulating film is formed, so as to level an upper surface of the inter-layer insulating film. The inter-layer insulating film is formed by using a droplet jetting method and the formation of the inter-layer insulating film includes at least a first step of forming an inter-layer

insulating film whose film thickness is changed so as to fill concave portions in the concavo-convex shape with the insulating film.

In the method disclosed in JP 08-236,908, liquid photosensitive resin 3 is deposited on areas where no conductive patterns 2 are formed. Therefore, as shown in part (b) in Fig. 1, the top face after the deposition is not even, and V-shaped gaps are formed in a sectional view at each boundary between the liquid photosensitive resin 3 and the conductive patterns 2. In order to fill the gaps, an additional process of depositing the liquid photosensitive resin 3 is provided. However, when this process is performed using spray coating or the like, Applicant respectfully submits that the top face is still not uniformly even (against part (c) in Fig. 2).

In contrast, the claimed invention includes forming the inter-layer insulating film by changing the film thickness of the inter-layer insulating film according to a concavo-convex shape of an area where the inter-layer insulating film is formed. JP 08-236,908 does not disclose or suggest such changing of the film thickness according to a concavo-convex shape. Neither does Speakman. Accordingly, the combination of JP 08-236,908 and Speakman cannot render claim 1 obvious. Accordingly, reconsideration and withdrawal of the rejection of claim 1 is respectfully requested.

Claim 2 is cancelled. Accordingly, this rejection is moot.

Claim 6 depends from claim 1 and should be allowable for at least the same reasons as set forth above.

Claims 3-5, 7 and 8 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over JP 08-236908 in combination with Speakman (U.S. Pat. No. 5,603,831) and further in combination with JP 10-221,698. This rejection is respectfully

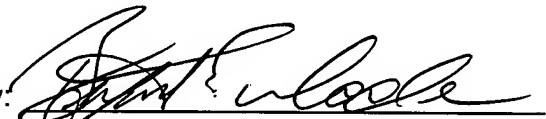
traversed. Claims 3-5, 7 and 8 depend from claim 1 and should be allowable for at least the same reasons as set forth above.

### CONCLUSION

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action and the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

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